

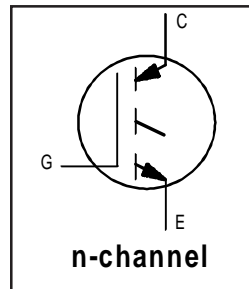
IRG4RC10U

INSULATED GATE BIPOLAR TRANSISTOR

UltraFast Speed IGBT

Features

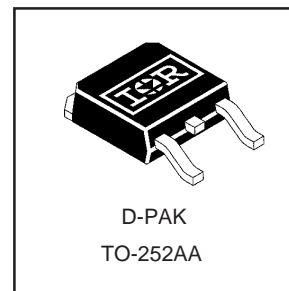
- UltraFast: Optimized for high operating frequencies (8-40 kHz in hard switching, >200 kHz in resonant mode)
- Generation 4 IGBT design provides tighter parameter distribution and higher efficiency than previous generation
- Industry standard TO-252AA package



| |
|-----------------------------------|
| $V_{CES} = 600V$ |
| $V_{CE(on)} \text{ typ.} = 2.15V$ |
| @ $V_{GE} = 15V, I_C = 5.0A$ |

Benefits

- Generation 4 IGBT's offer highest efficiency available
- IGBT's optimized for specified application conditions



Absolute Maximum Ratings

| | Parameter | Max. | Units |
|---------------------------|------------------------------------|------------------------------------|------------|
| V_{CES} | Collector-to-Emitter Voltage | 600 | V |
| $I_C @ T_C = 25^\circ C$ | Continuous Collector Current | 8.5 | A |
| $I_C @ T_C = 100^\circ C$ | Continuous Collector Current | 5.0 | |
| I_{CM} | Pulsed Collector Current ① | 34 | |
| I_{LM} | Clamped Inductive Load Current ② | 34 | |
| V_{GE} | Gate-to-Emitter Voltage | ± 20 | V |
| E_{ARV} | Reverse Voltage Avalanche Energy ③ | 110 | mJ |
| $P_D @ T_C = 25^\circ C$ | Maximum Power Dissipation | 38 | W |
| $P_D @ T_C = 100^\circ C$ | Maximum Power Dissipation | 15 | |
| T_J | Operating Junction and | -55 to +150 | $^\circ C$ |
| T_{STG} | Storage Temperature Range | | |
| | Soldering Temperature, for 10 sec. | 300 (0.063 in. (1.6mm) from case) | |

Thermal Resistance

| | Parameter | Typ. | Max. | Units |
|-----------------|----------------------------------|------------|------|--------------|
| $R_{\theta JC}$ | Junction-to-Case | — | 3.3 | $^\circ C/W$ |
| $R_{\theta JA}$ | Junction-to-Ambient (PCB mount)* | — | 50 | |
| Wt | Weight | 0.3 (0.01) | — | g (oz) |

* When mounted on 1" square PCB (FR-4 or G-10 Material).

For recommended footprint and soldering techniques refer to application note #AN-994

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Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

| | Parameter | Min. | Typ. | Max. | Units | Conditions |
|---------------------------------|--|------|------|-----------|---------|--|
| $V_{(BR)CES}$ | Collector-to-Emitter Breakdown Voltage | 600 | — | — | V | $V_{GE} = 0V, I_C = 250\mu A$ |
| $V_{(BR)ECS}$ | Emitter-to-Collector Breakdown Voltage ④ | 14 | — | — | V | $V_{GE} = 0V, I_C = 1.0A$ |
| $\Delta V_{(BR)CES}/\Delta T_J$ | Temperature Coeff. of Breakdown Voltage | — | 0.54 | — | V/°C | $V_{GE} = 0V, I_C = 1.0mA$ |
| $V_{CE(ON)}$ | Collector-to-Emitter Saturation Voltage | — | 2.15 | 2.6 | V | $I_C = 5.0A$ $V_{GE} = 15V$ See Fig.2, 5 |
| | | — | 2.61 | — | | |
| | | — | 2.30 | — | | |
| $V_{GE(th)}$ | Gate Threshold Voltage | 3.0 | — | 6.0 | | $I_C = 5.0A, T_J = 150^\circ\text{C}$ $V_{CE} = V_{GE}, I_C = 250\mu A$ |
| $\Delta V_{GE(th)}/\Delta T_J$ | Temperature Coeff. of Threshold Voltage | — | -8.7 | — | mV/°C | $V_{CE} = V_{GE}, I_C = 250\mu A$ |
| g_{fe} | Forward Transconductance ⑤ | 2.8 | 4.2 | — | S | $V_{CE} = 100V, I_C = 5.0A$ |
| I_{CES} | Zero Gate Voltage Collector Current | — | — | 250 | μA | $V_{GE} = 0V, V_{CE} = 600V$ $V_{GE} = 0V, V_{CE} = 10V, T_J = 25^\circ\text{C}$ $V_{GE} = 0V, V_{CE} = 600V, T_J = 150^\circ\text{C}$ |
| | | — | — | 2.0 | | |
| | | — | — | 1000 | | |
| I_{GES} | Gate-to-Emitter Leakage Current | — | — | ± 100 | nA | $V_{GE} = \pm 20V$ |

Switching Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

| | Parameter | Min. | Typ. | Max. | Units | Conditions |
|--------------|-----------------------------------|------|------|------|-------|--|
| Q_g | Total Gate Charge (turn-on) | — | 15 | 22 | nC | $I_C = 5.0A$ $V_{CC} = 400V$ $V_{GE} = 15V$ See Fig. 8 |
| Q_{ge} | Gate - Emitter Charge (turn-on) | — | 2.6 | 4.0 | | |
| Q_{gc} | Gate - Collector Charge (turn-on) | — | 5.8 | 8.7 | | |
| $t_{d(on)}$ | Turn-On Delay Time | — | 19 | — | ns | $T_J = 25^\circ\text{C}$ $I_C = 5.0A, V_{CC} = 480V$ $V_{GE} = 15V, R_G = 100\Omega$ Energy losses include "tail" See Fig. 9, 10, 14 |
| t_r | Rise Time | — | 11 | — | | |
| $t_{d(off)}$ | Turn-Off Delay Time | — | 116 | 240 | | |
| t_f | Fall Time | — | 81 | 180 | | |
| E_{on} | Turn-On Switching Loss | — | 0.08 | — | mJ | See Fig. 9, 10, 14 |
| E_{off} | Turn-Off Switching Loss | — | 0.16 | — | | |
| E_{ts} | Total Switching Loss | — | 0.24 | 0.36 | mJ | $T_J = 150^\circ\text{C},$ $I_C = 5.0A, V_{CC} = 480V$ $V_{GE} = 15V, R_G = 100\Omega$ Energy losses include "tail" See Fig. 11, 14 |
| $t_{d(on)}$ | Turn-On Delay Time | — | 18 | — | | |
| t_r | Rise Time | — | 14 | — | | |
| $t_{d(off)}$ | Turn-Off Delay Time | — | 180 | — | | |
| t_f | Fall Time | — | 150 | — | | |
| L_E | Internal Emitter Inductance | — | 7.5 | — | nH | Measured 5mm from package |
| C_{ies} | Input Capacitance | — | 270 | — | pF | $V_{GE} = 0V$ $V_{CC} = 30V$ $f = 1.0MHz$ See Fig. 7 |
| C_{oes} | Output Capacitance | — | 21 | — | | |
| C_{res} | Reverse Transfer Capacitance | — | 3.5 | — | | |

Notes:

- ① Repetitive rating; $V_{GE} = 20V$, pulse width limited by max. junction temperature. (See fig. 13b)
- ② $V_{CC} = 80\%(V_{CES}), V_{GE} = 20V, L = 10\mu H, R_G = 100\Omega,$ (See fig. 13a)
- ③ Repetitive rating; pulse width limited by maximum junction temperature.
- ④ Pulse width $\leq 80\mu s$; duty factor $\leq 0.1\%$.
- ⑤ Pulse width $5.0\mu s$, single shot.

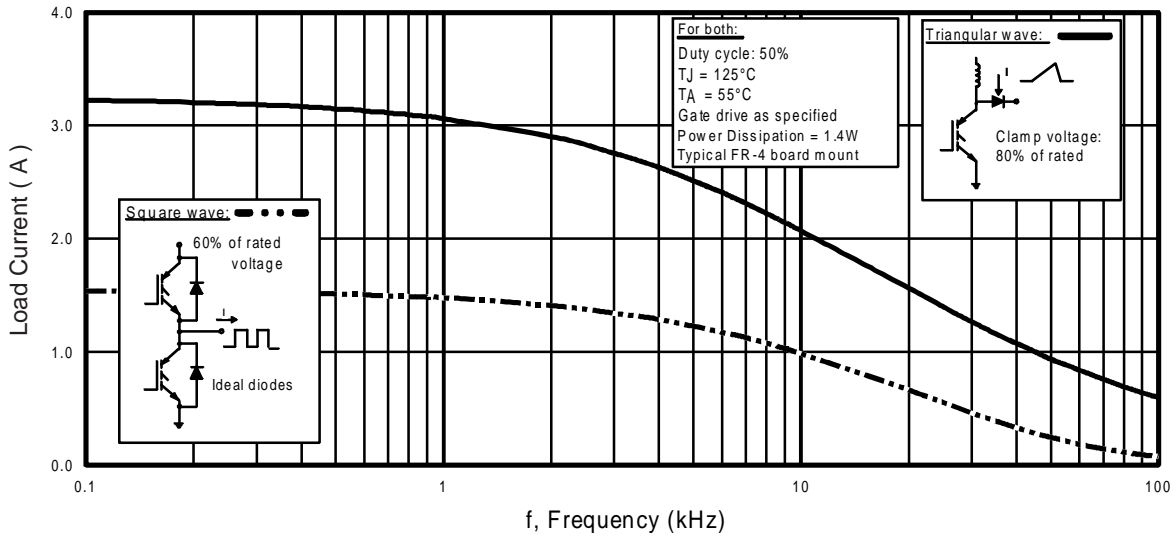


Fig. 1 - Typical Load Current vs. Frequency
(Load Current = I_{RMS} of fundamental)

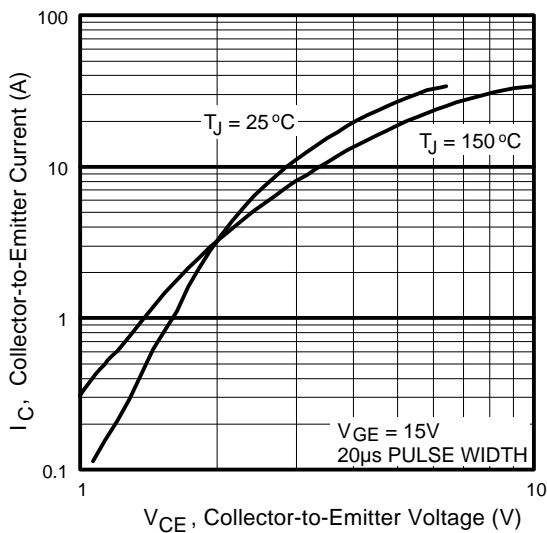


Fig. 2 - Typical Output Characteristics
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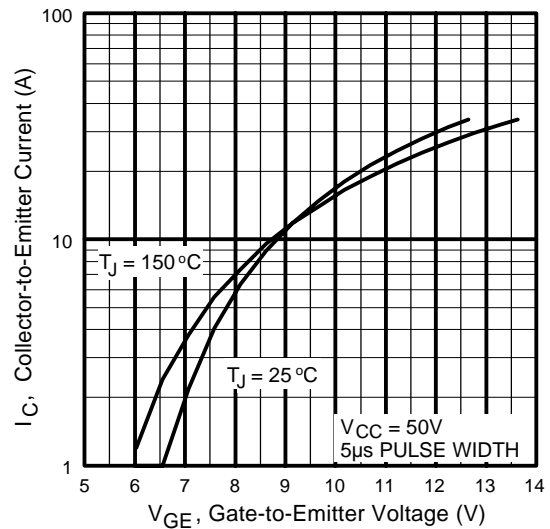


Fig. 3 - Typical Transfer Characteristics

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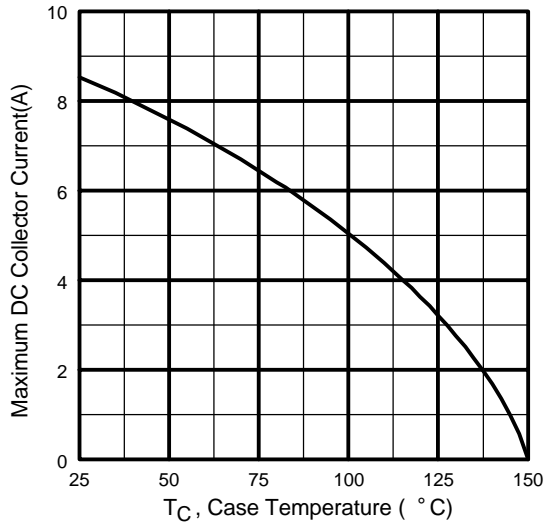


Fig. 4 - Maximum Collector Current vs. Case Temperature

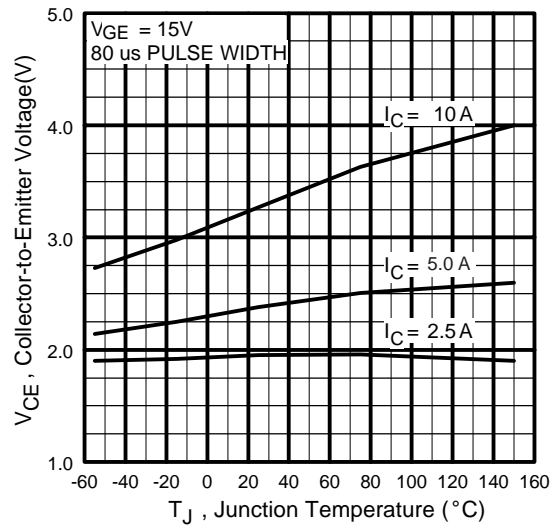


Fig. 5 - Typical Collector-to-Emitter Voltage vs. Junction Temperature

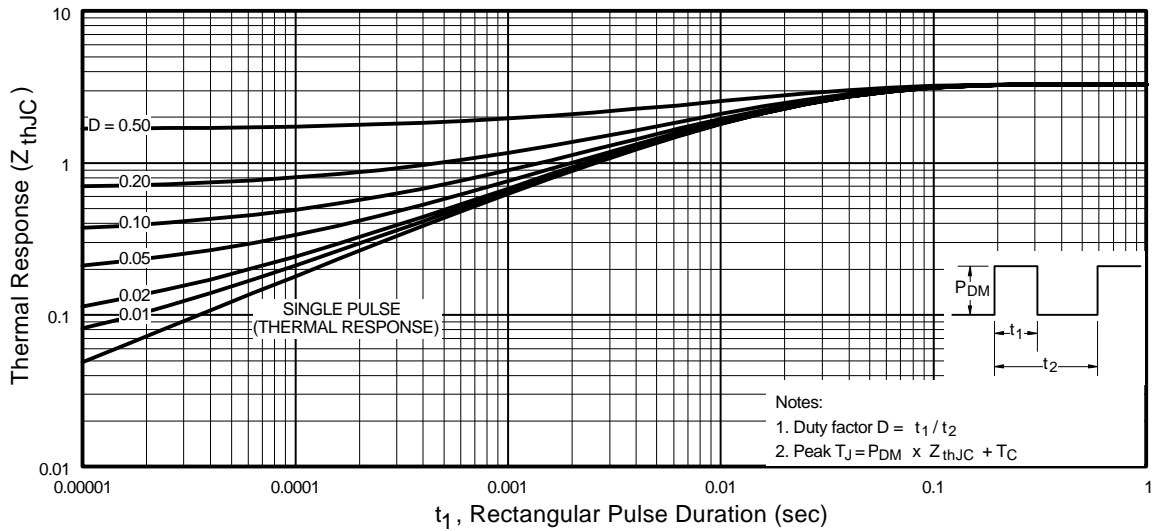


Fig. 6 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

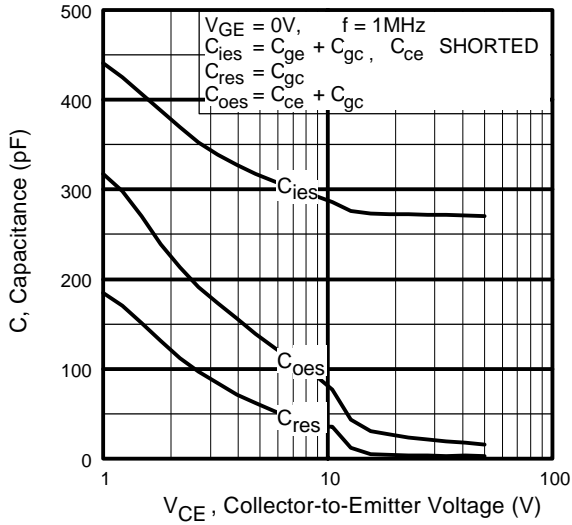


Fig. 7 - Typical Capacitance vs. Collector-to-Emitter Voltage

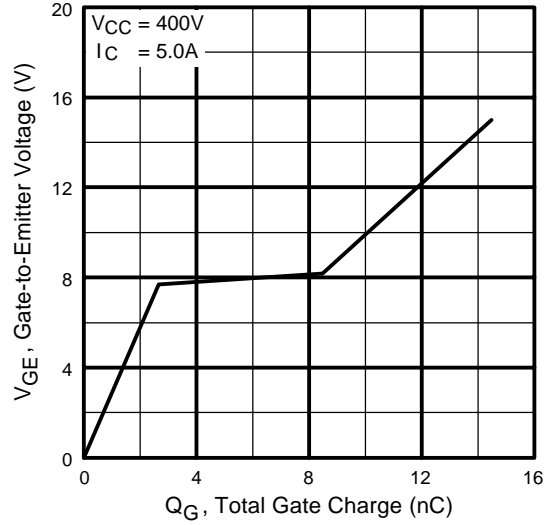


Fig. 8 - Typical Gate Charge vs. Gate-to-Emitter Voltage

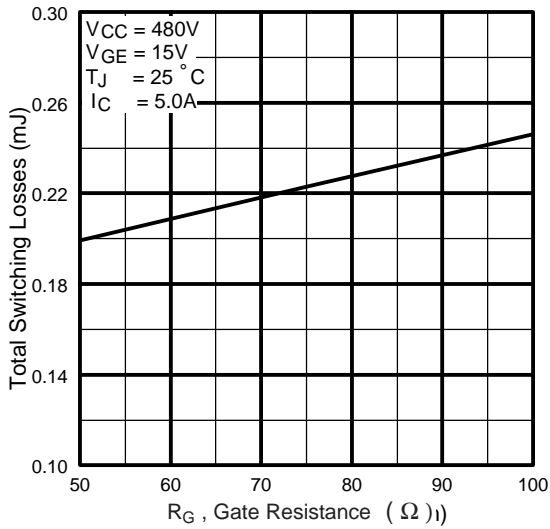


Fig. 9 - Typical Switching Losses vs. Gate Resistance

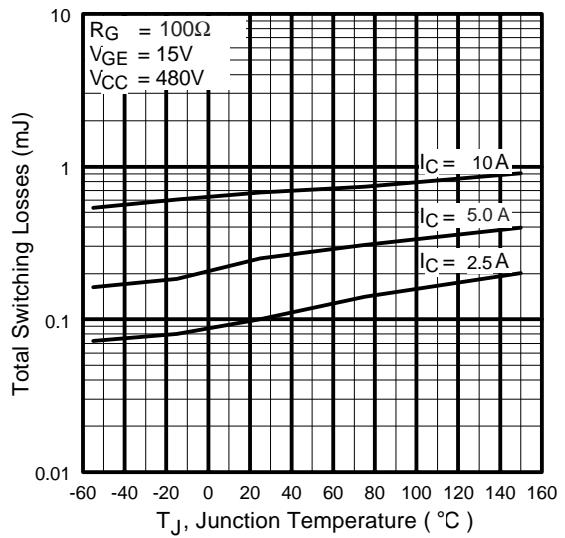


Fig. 10 - Typical Switching Losses vs. Junction Temperature

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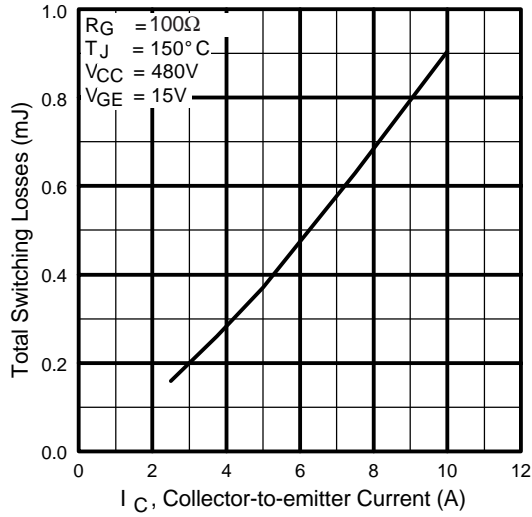


Fig. 11 - Typical Switching Losses vs. Collector-to-emitter Current

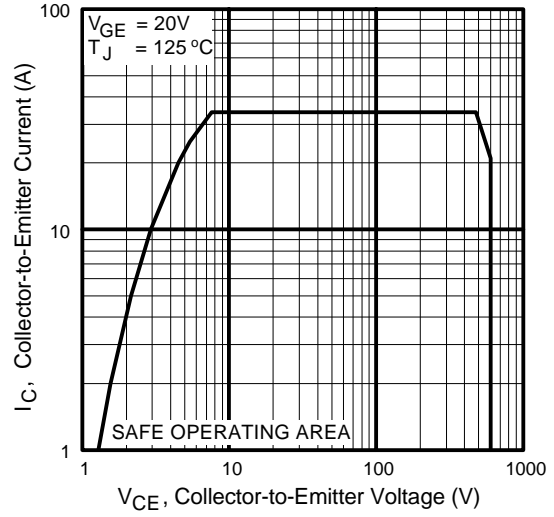


Fig. 12 - Turn-Off SOA

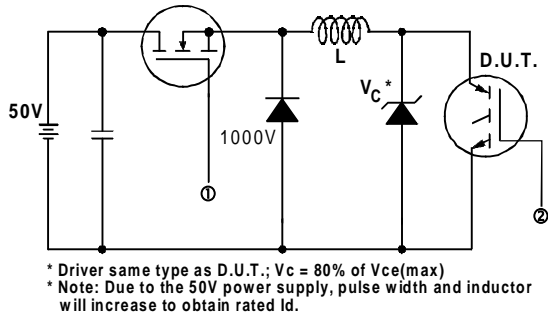


Fig. 13a - Clamped Inductive Load Test Circuit

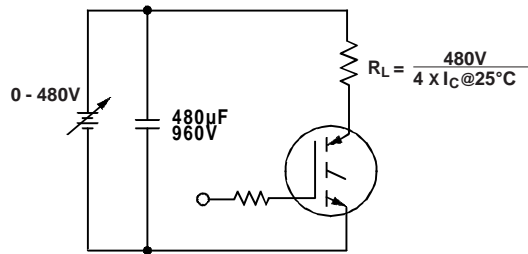


Fig. 13b - Pulsed Collector Current Test Circuit

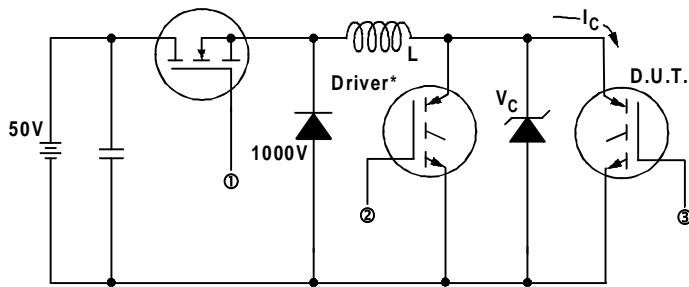


Fig. 14a - Switching Loss Test Circuit

* Driver same type as D.U.T., $V_C = 480\text{V}$

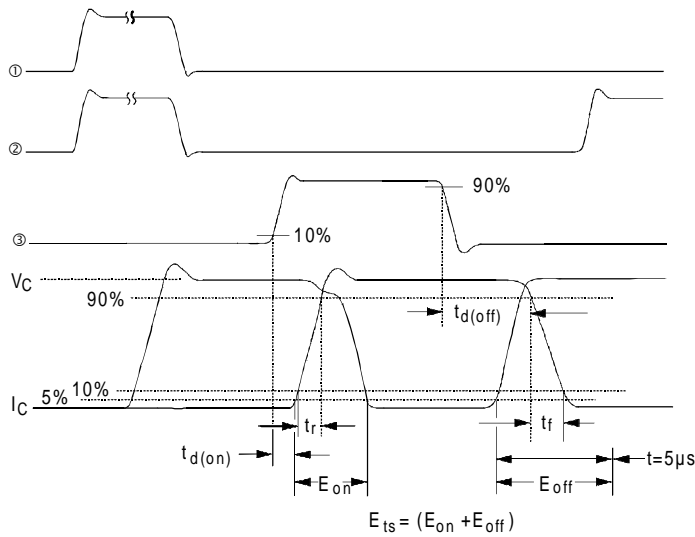
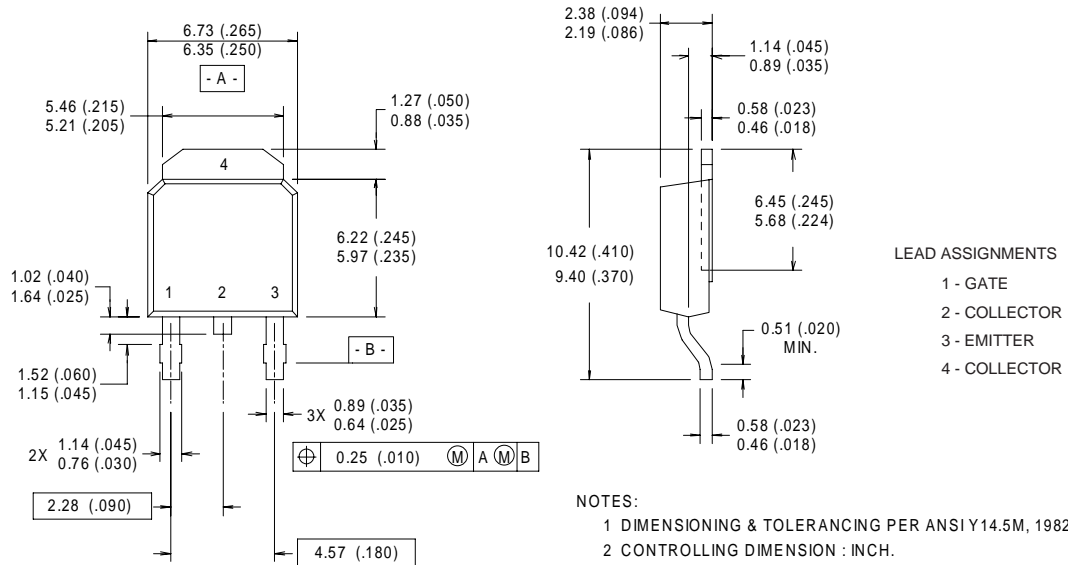


Fig. 14b - Switching Loss Waveforms

Package Outline

TO-252AA Outline

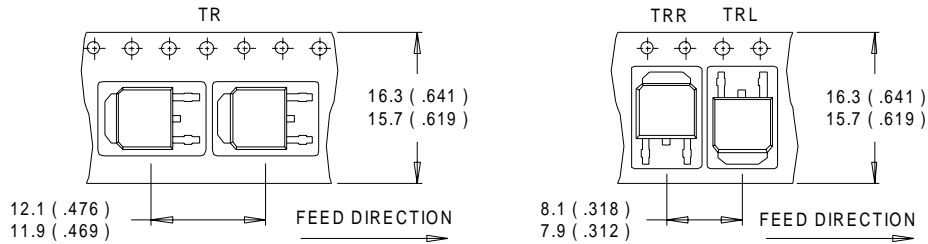
Dimensions are shown in millimeters (inches)



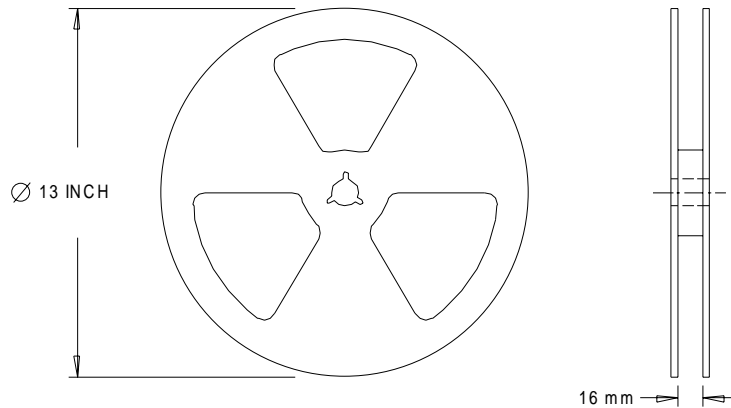
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Tape & Reel Information TO-252AA



- NOTES :
1. CONTROLLING DIMENSION : MILLIMETER.
 2. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).
 3. OUTLINE CONFORMS TO EIA-481 & EIA-541.



- NOTES :
1. OUTLINE CONFORMS TO EIA-481.

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Note: For the most current drawings please refer to the IR website at:
<http://www.irf.com/package/>